

WHAT IS CLAIMED IS:

Please cancel claims 1-11, 27, and 28, without prejudice or disclaimer.

Claims 1 – 11. (Cancelled)

12. (Currently amended) A method for forming an optoelectronic device comprising the steps of:

providing a substrate having a patterned first electrode on a surface thereof;

providing a holed layer on the surface of the substrate having the first patterned electrode, the holed layer being permanently attached to the substrate and defining a first set of holes through which the patterned first electrode is exposed;

applying a first light-emissive material to the surface of the holed layer opposite the substrate[[]];

displacing the first light-emissive material in fluid form across the surface of the holed layer so as to selectively deposit the material only in the first set of holes of the holed layer;

solidifying the first light-emissive material; and

forming a second electrode on the solidified first light-emissive material in the first set of holes such that charge carriers can move between the first light-emissive material and the second electrode.

13. (Previously presented) A method for forming an optoelectronic device according to claim 12 comprising providing the holed layer by laminating a polymer layer with pre-formed holes to the surface of the substrate.

14. (Previously presented) A method for forming an optoelectronic device according to claim 12 comprising providing the holed layer by providing a layer of a polymer on the surface of the substrate having the patterned first electrode, and then forming the first set of holes in the polymer layer.

15. (Previously presented) A method for forming an optoelectronic device according to claim 14 comprising forming the first set of holes by etching.

16. (Previously presented) A method for forming an optoelectronic device according to claim 12 wherein the patterned first electrode comprises a two-dimensional array of discrete pixel electrodes.

17. (Currently amended) A method according to claim 16 wherein the first set of holes ~~expose~~ exposes only some of the discrete pixel electrodes.

18. (Currently amended) A method according to claim ~~12~~ 17 further comprising forming a second set of holes in the holed layer to expose discrete pixel electrodes which were not exposed by the first set of holes in the holed layer, depositing a layer of second light-emissive material in the second set of holes, and forming a third electrode on the layers of second light-emissive material such that charge carriers can move between the layers of second light-emissive material and the third electrode.

19. (Previously presented) A method according to claim 18 comprising additionally forming the second electrode over substantially the entire surface of the holed layer opposite the substrate, and forming the second set of holes by etching through the second electrode and the holed layer.

20. (Currently amended) A method according to claim 19 further comprising forming a third set of holes in the holed layer to expose further discrete pixel electrodes which were not exposed by the first or second set sets of holes, depositing a layer of third light-emissive material in the third set of holes, and forming a fourth electrode on the layers of third light-emissive material such that charge carriers can move between the fourth electrode and the layers of third light-emissive material.

21. (Original) A method according to claim 20 wherein the first, second and third light-emissive materials are each capable of emitting light of the three primary colours respectively.

22. (Previously presented) A method according to claim 12 further comprising the step of forming a layer of a charge transport material in the first set of holes.

23. (Previously presented) A method according to claim 22 comprising depositing the layer of charge transport material in the first set of holes by applying the charge transport material to the surface of the holed layer and displacing the charge transport material in a fluid form across the surface of the holed layer whereby the charge transport material is deposited in the first set of holes.

24. (Currently amended) A method for forming an optoelectronic device according to ~~any~~ claim 12 comprising depositing the second electrode without first removing the holed layer.

25. (Previously presented) A method for forming an optoelectronic device according to claim 20 comprising forming the second, third and fourth electrodes without removing the holed layer.

26. (Previously presented) An optoelectronic device produced by the method of claim 12.

Claims 27 and 28. (Cancelled)

Please add new claims 29-31, as follows:

29. (New) A method according to claim 12 further comprising the step of forming a layer of a hole injection material in the first set of holes between the patterned first electrode and the first light emitting material.

30. (New) A method according to claim 29 comprising depositing the layer of hole injection material in the first set of holes by applying the hole injection material in a solvent to the surface of the holed layer and displacing the hole injection material in a fluid form across the surface of the holed layer whereby the hole injection material is deposited in the first set of holes.

31. (New) A method according to claim 30 comprising evaporating the solvent prior to applying the first light-emissive layer.